

STP80NF12

Datasheet - production data

N-channel 120 V, 0.013 Ω typ., 80 A, STripFET™ II Power MOSFET in a TO-220 package

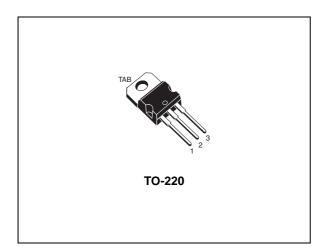
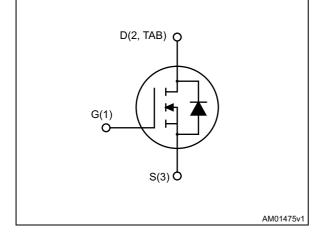


Figure 1. Internal schematic diagram



Features

Туре	V _{DSS}	R _{DS(on)} max	I _D	
STP80NF12	120 V	< 0.018 Ω	80 A	

- Exceptional dv/dt capability
- 100% avalanche tested
- Application oriented characterization

Application

• Switching applications

Description

This MOSFET series realized with STMicroelectronics unique STripFET process has specifically been designed to minimize input capacitance and gate charge. It is therefore suitable as primary switch in advanced highefficiency, high-frequency isolated DC-DC converters for telecom and computer applications. It is also intended for any applications with low gate drive requirements.

Table 1. Device summary

Order code Marking		Package	Packaging
STP80NF12	STP80NF12 P80NF12		Tube

DocID9204 Rev 8

This is information on a product in full production.

Contents

1	Electrical ratings 2
2	Electrical characteristics
	2.1 Electrical characteristics (curves)
3	Test circuits
4	Package mechanical data 8
5	Revision history



1 Electrical ratings

Symbol	Parameter	Value	Unit
V _{DS}	Drain-source voltage ($V_{GS} = 0$)	120	V
V _{GS}	Gate-source voltage	± 20	V
I _D ⁽¹⁾	Drain current (continuous) at $T_{C} = 25 \text{ °C}$	80	А
Ι _D	Drain current (continuous) at T _C =100 °C	60	А
I _{DM} ⁽²⁾	Drain current (pulsed)	320	А
P _{TOT}	Total dissipation at $T_{C} = 25 \text{ °C}$	300	W
	Derating factor	2.0	W/°C
dv/dt ⁽³⁾	Peak diode recovery voltage slope	10	V/ns
E _{AS} ⁽⁴⁾	Single pulse avalanche energy	350	mJ
Т _Ј T _{stg}	Operating junction temperature Storage temperature	-55 to 175	°C

1. Limited by package

2. Pulse width limited by safe operating area

3. I_{SD} < 80 A, di/dt < 300 A/µs, V_{DD} = 80% $V_{(BR)DSS}$

4. Starting $T_J = 25 \text{ °C}$, $I_D = 40 \text{ A}$, $V_{DD} = 50 \text{ V}$

	Table	3.	Thermal	data
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Symbol Parameter		Value	Unit
R _{thJC}	Thermal resistance junction-case max	0.5	°C/W
R _{thJA}	Thermal resistance junction-ambient max	62.5	°C/W
TI Maximum lead temperature for soldering purpose		300	°C



2 Electrical characteristics

(T_{CASE} = 25 °C unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage	$I_{D} = 250 \ \mu A, \ V_{GS} = 0$	120			V
I _{DSS}	Zero gate voltage drain current (V _{GS} = 0)	V _{DS} = max rating V _{DS} = max rating @125°C			1 10	μΑ μΑ
I _{GSS}	Gate body leakage current (V _{DS} = 0)	$V_{GS} = \pm 20 V$			±100	nA
V _{GS(th)}	Gate threshold voltage	V_{DS} = V_{GS} , I_D = 250 μ A	2		4	V
R _{DS(on)}	Static drain-source on resistance	V _{GS} = 10 V, I _D = 40 A		0.013	0.018	Ω

Table	4.	On/	off	states
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Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
9 _{fs} ⁽¹⁾	Forward transconductance	V _{DS} =15 V, I _D = 40 A	-	80		S
C _{iss}	Input capacitance	V _{DS} =25 V, f=1 MHz, V _{GS} =0	-	4300		pF
C _{oss}	Output capacitance		-	600		pF
C _{rss}	Reverse transfer capacitance		-	230		pF
Q _{gs}	Total gate charge	$V_{DD} = 80 \text{ V}, \text{ I}_{D} = 80 \text{ A}$ $V_{GS} = 10 \text{ V}$	-	140	189	nC
Q _{gs}	Gate-source charge		-	23		nC
Q _{gd}	Gate-drain charge	.62	-	51		nC

1. Pulsed: pulse duration=300µs, duty cycle 1.5%

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{d(on)}	Turn-on delay time		-	40	-	ns
t _r	Rise time	$V_{DD}=50 \text{ V}, I_{D}=40 \text{ A},$ $R_{G}=4.7 \Omega, V_{GS}=10 \text{ V}$ See <i>Figure 13</i>	-	145	-	ns
t _{d(off)}	Turn-off delay time		-	134	-	ns
t _f	Fall time		-	115	-	ns



Symbol	Parameter	Test conditions	Min.	Тур.	Max	Unit
I _{SD}	Source-drain current		-	-	80	А
I _{SDM} ⁽¹⁾	Source-drain current (pulsed)		-	-	320	А
$V_{SD}^{(2)}$	Forward on voltage	I _{SD} =80 A, V _{GS} =0	-	-	1.3	V
t _{rr}	Reverse recovery time	I _{SD} =80 A,	-	155		ns
Q _{rr}	Reverse recovery charge	di/dt = 100 A/µs,	-	0.85		μC
I _{RRM}	Reverse recovery current	V _{DD} =35 V, T _J = 150 °C	-	11		А

Table 7. Source drain diode

1. Pulse width limited by safe operating area

2. Pulsed: pulse duration = $300 \ \mu$ s, duty cycle 1.5%



Electrical characteristics (curves) 2.1

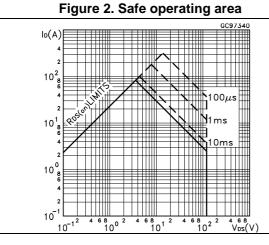


Figure 4. Output characteristics

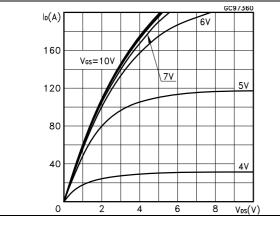
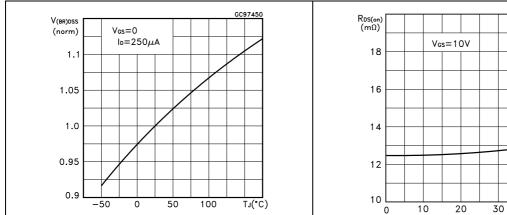


Figure 6. Normalized B_{VDSS} vs. temperature



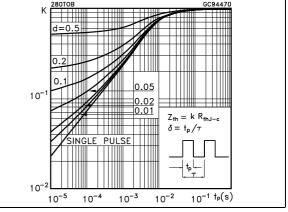


Figure 3. Thermal impedance

Figure 5. Transfer characteristics

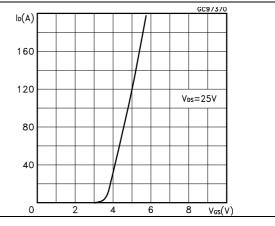


Figure 7. Static drain-source on resistance

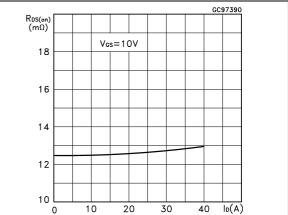


Figure 8. Gate charge vs. gate-source voltage

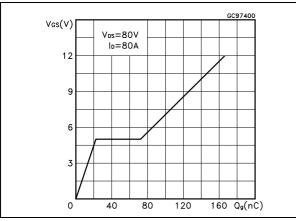


Figure 10. Normalized gate threshold voltage vs. temperature

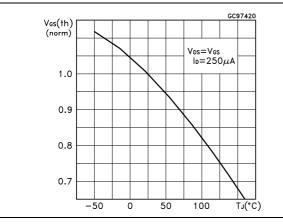
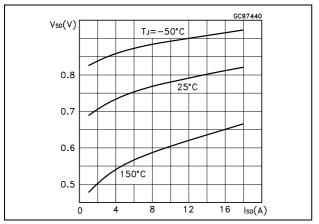


Figure 12. Source-drain diode forward characteristics



57

Figure 9. Capacitance variations

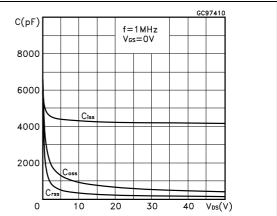
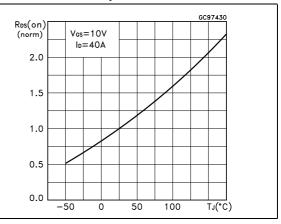


Figure 11. Normalized on resistance vs. temperature



3 **Test circuits**

Figure 13. Switching times test circuit for resistive load

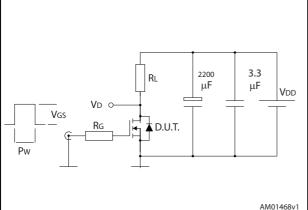


Figure 15. Test circuit for inductive load switching and diode recovery times

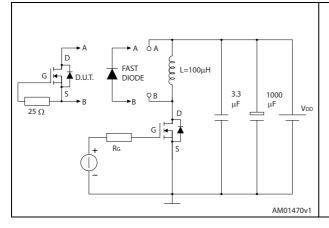


Figure 17. Unclamped inductive waveform

VD

V(BR)DSS

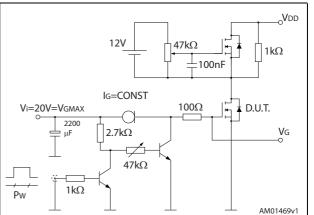
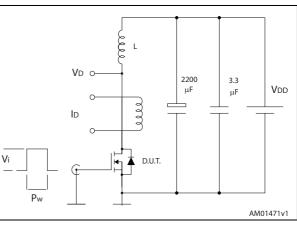


Figure 14. Gate charge test circuit





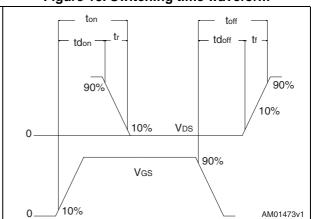
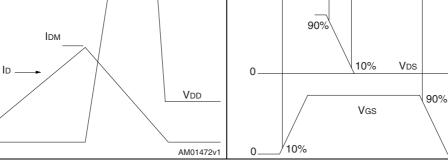


Figure 18. Switching time waveform

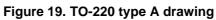


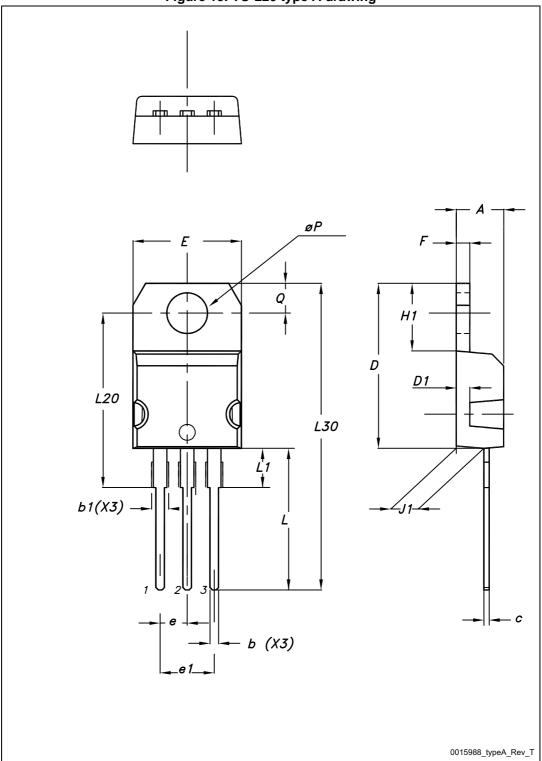
Vdd

4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK[®] is an ST trademark.









Dim. —	mm		
	Min.	Тур.	Max.
А	4.40		4.60
b	0.61		0.88
b1	1.14		1.70
С	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10		10.40
е	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13		14
L1	3.50		3.93
L20		16.40	
L30		28.90	
Øр	3.75		3.85
Q	2.65		2.95

Table 8. TO-220 type A mechanical data



5 Revision history

Table 9. Revision history			
Date	Revision	Changes	
21-Jun-2004	2	Preliminary version	
24-Jul-2006	3	The document has been reformatted, SOA updated	
31-Jan-2007	4	Typo mistake on <i>Table 2</i> .	
10-Apr-2007	5	Typo mistake on Table 2 and Table 3	
19-Apr-2007	6	Corrected value on Table 4	
17-Nov-2008	7	Inserted E _{AS} value on <i>Table 2</i> .	
26-Feb-2014	8	Updated: Section 4: Package mechanical data Inserted E _{AS} value on Table 2. Added value V _{GS} on Table 4	

Table 9. Revision history



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